

## Status of the EUDET Prototype

#### **Benjamin Lutz**

for the AHCAL developers







#### Status of Modules' developments:

-Flexible Interconnection Foils (POWER, SIGNAL)
-Prototype Cassette
-Reflector Foils
-POWER
-CALIB
-HBU
-DIF firmware

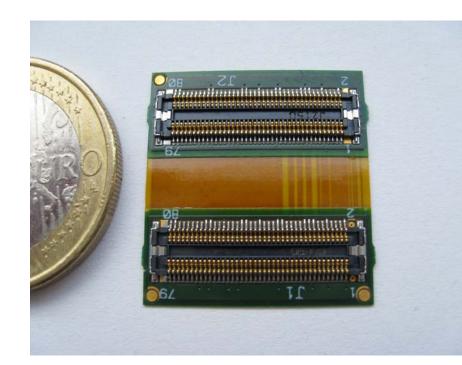
### **Timeline issues**

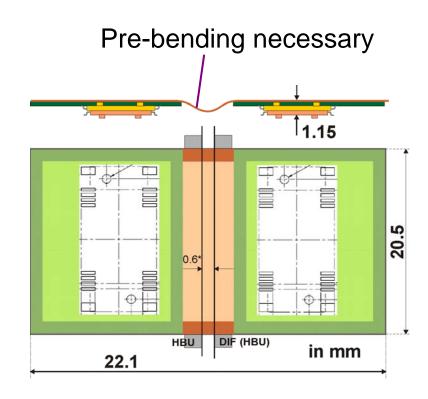


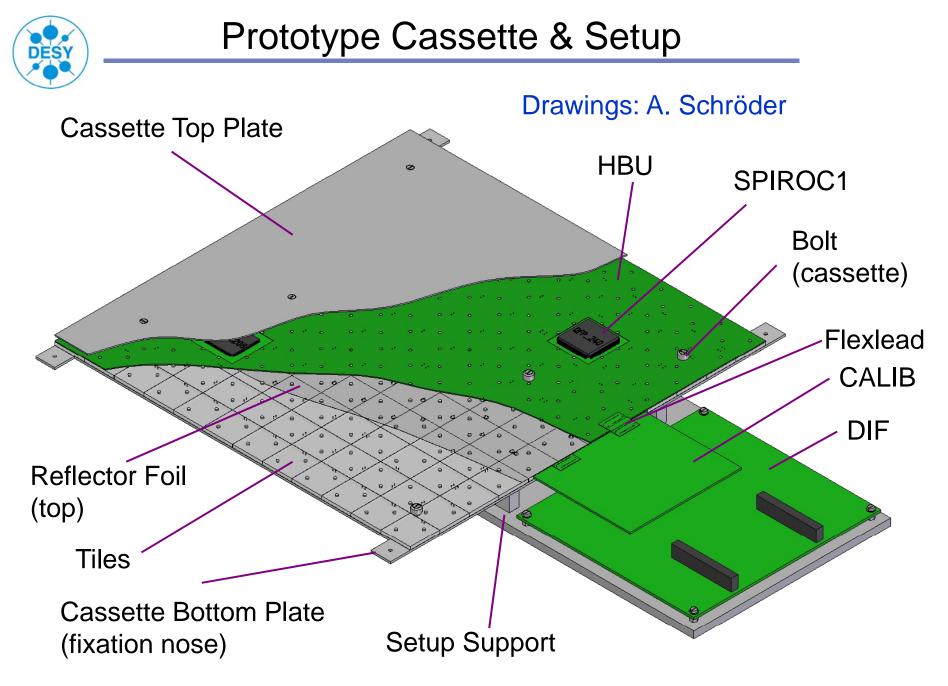
Flexleads finished (20 pieces of each type).

Tests can be performed when HBU arrives.

Interconnection between the 6 HBUs of a slab, and between HBU0 and the DIF. 2 types have been realized: SIGNAL and POWER flexleads.

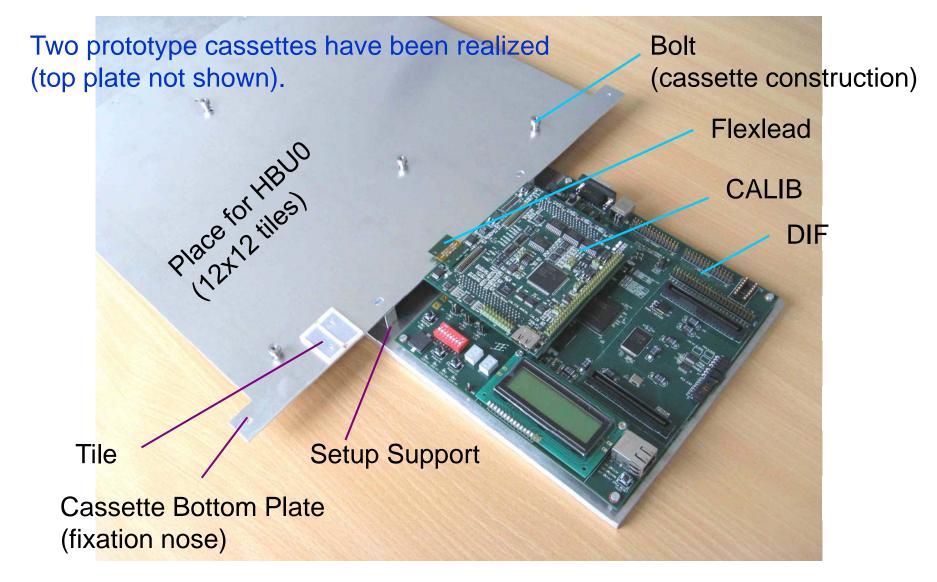


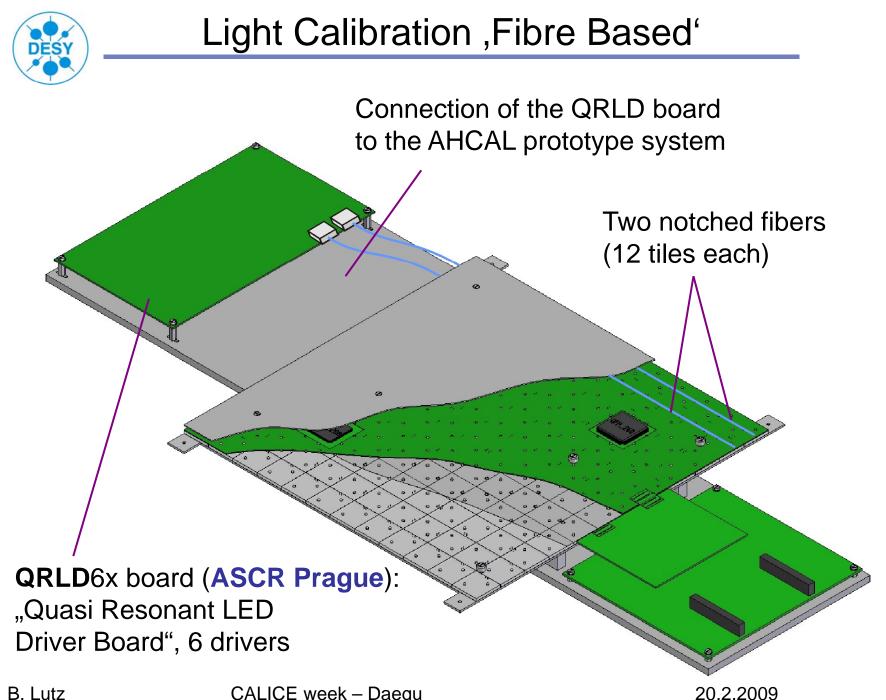






### Prototype Cassette & Setup

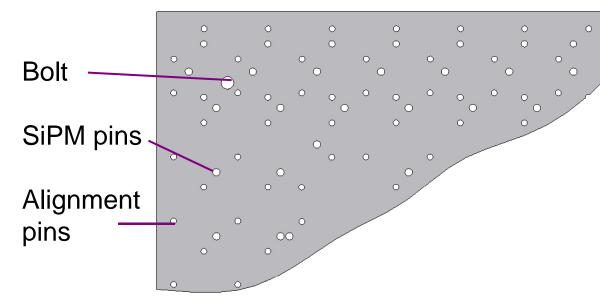




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**Reflector Foils** 



The reflector foils are placed below and on top of the tiles. The upper foil has about 500 laser-cut holes (alignment pins, SiPM pins, cassette contruction).

Reflector Foils arrived at DESY mid Jan.

Problems: Foils are curled, reason is unknown up to now (moisture?).

⇒Foil must be glued to PCB with high accuracy (holes in PCB and foil must fit)





System can be operated without POWER module (bench-top power supplies) => production shifted to early 2009

Schematic is finished.

Layout: starting within these days, similar shape as CALIB module.

The POWER module carries the power regulators for the AHCAL electronics. It enables the ILC power-cycling of the innerdetector electronics as well as the current- and voltage sensors.



# CALIB module

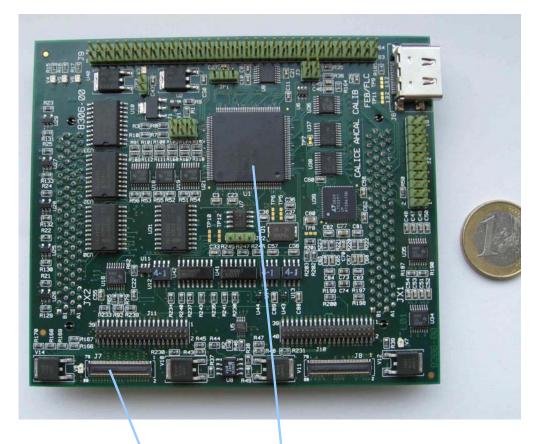
CALIB Module finished (4 pieces)

μC programming in progress.

Tests are currently ongoing in stand-alone mode.

For final tests the HBU is needed.

The CALIB module operates the AHCAL specific light calibration system and the readout of the temperature and voltage/current sensors.

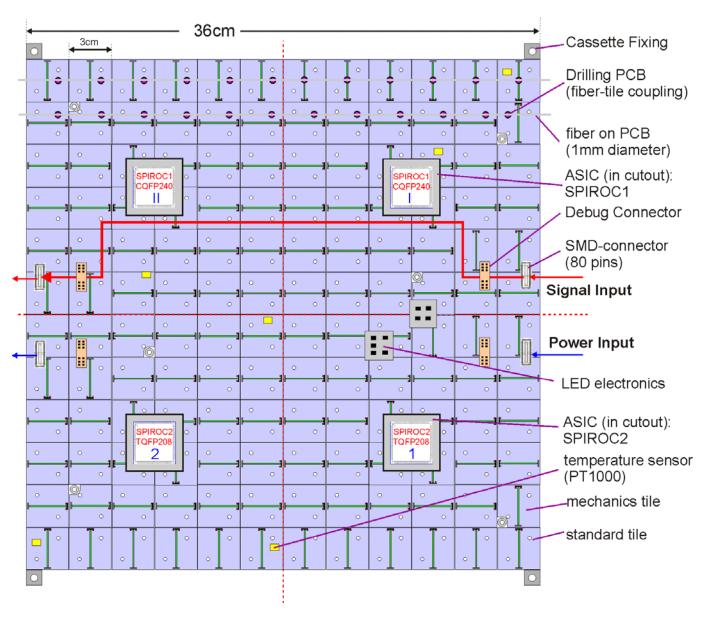


ARM7 µController

Interface to HBU (flexleads)

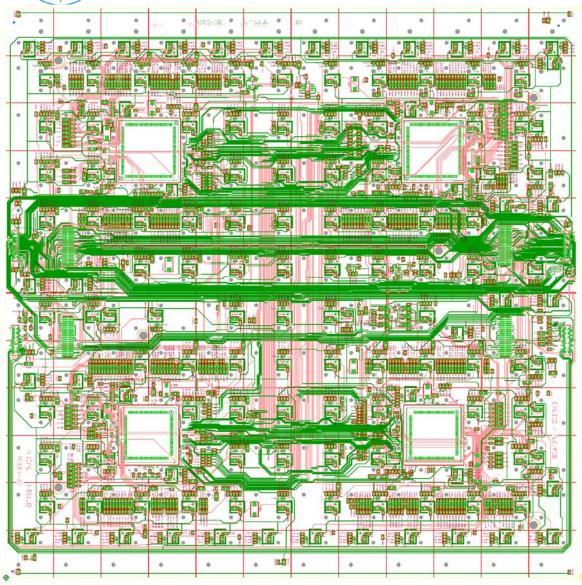


### HBU0 module (old view)





# HBU0 module



PCBs are in production.

PCB has 6 layers (only 2 layers shown), with cutouts for SPIROCs.

Typical size: 36x36cm<sup>2</sup> (144 detector channels)

The HBU integrates 144 scintillating tiles with MGPDs together with 4 SPIROCs and the AHCAL light calibration system (2 types)

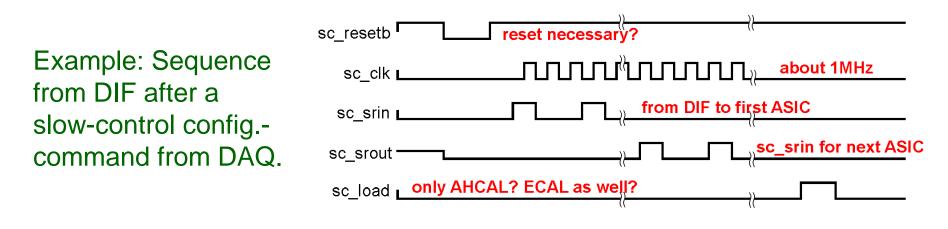


DIF-DAQ interface defined within DIF task force, see: <a href="http://adweb.desy.de/~reinecke/DIF\_Firmware\_vers1\_9.pdf">http://adweb.desy.de/~reinecke/DIF\_Firmware\_vers1\_9.pdf</a>

AHCAL: USB-DIF interface has been set up first (Labview), LDA follows afterwards.

Timing diagrams DIF-ASICs (SPIROCs) have been developed in a preliminary version

First system with basic operations expected beginning of March.





The HBU0 / HBU modules determine the timelines:
-HBU0 PCB expected early March., ordered at 2 companies (PCB complexity)
-HBU0 tiles have been produced (ITEP).
-ASICs (SPIROC1 and SPIROC2, packaged) should arrive end of Feb.
-Assembly within 2 weeks (SMD components, tiles)

Challenging timeline for the modules' redesigns (EUDET ,layer-module'), minimum required:

- -HBU: only one type of ASICs. HBU0 test results define redesign. HBU redesign needs input of tile shape and SPIROC pinout.
- -DIF (replace commercial board). Firmware development has to take place ,step-by-step' in parallel to DAQ-DIF setup. Flexleads, CALIB and POWER could be used for final setup (to be discussed).



-Timeline is challenging for EUDET layer module:

- timeline does not include perhaps necessary redesigns.

-Prototype system, based on USB control, expected beginning of April

-Redesigns for ,Layer Module' require preconditions fulfilled: successful prototype-operation,

mechanical boundaries within and at the end-face of the absorber structure, DAQ operation of the detector,

(the new) tile-dimensions, ASIC's pinout.

(=> minimize number of redesigns?).